

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S16	2	(endpoint adj detection) and optical and "CMP" and wafer and radiation and laser and pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 12:49
S17	8	(endpoint adj detection) and optical and "CMP" and wafer and radiation and laser and pulse and (thermal or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 12:50
S18	8	(endpoint adj detection) and optical and "CMP" and wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 12:50
S19	8	(endpoint adj detection) and "CMP" and wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:23
S20	276	"CMP" and wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:23
S21	0	"CMP" and wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$) and "374"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:23
S22	39	"CMP" and wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$) and "356"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:27
S23	10	"CMP" and wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$) and "451"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:24
S24	0	"CMP" and wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$) and "374"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:24

S25	12	wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$) and "451"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:26
S26	24	wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$) and "374"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:26
S28	220	wafer and radiation and laser and pulse and (thermal or temperature) and (thick\$) and "356"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:26
S29	4	"CMP" and wafer and (radiation NEAR (detect\$3 or sens\$3)) and laser and pulse and (thermal or temperature) and (thick\$) and "356"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/29 13:27
S30	321	374/131.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:46
S31	1117	374/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:46
S32	1162	374/141.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:46
S33	262	374/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:46
S34	83	374/6.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:46
S35	128	374/7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:46

S36	698	374/45.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:46
S37	416	374/57.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:47
S38	1730	451/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:47
S39	793	451/6.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:47
S40	211	451/7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:47
S41	925	451/8.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:47
S42	3277	451/41.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:47
S43	402	356/630.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/29 14:47